SCLS606B - MARCH 2005 - REVISED APRIL 2008

- Qualified for Automotive Applications
- Operating Range of 4.5 V to 5.5 V
- Max t_{pd} of 9.5 ns at 5 V
- Low Power Consumption, 20-μA Max I_{CC}
- ±8-mA Output Drive at 5 V
- Inputs Are TTL-Voltage Compatible
- ESD Protection Level Per AEC-Q100 Classification
 - 2000-V (H2) Human-Body Model
 - 200-V (M3) Machine Model
 - 1000-V (C5) Charged-Device Model

DBV OR DCK PACKAGE (TOP VIEW) A 1 5 VCC B 2 GND 3 4 Y

description/ordering information

The SN74AHCT1G32 is a single 2-input positive-OR gate. The device performs the Boolean function Y = A + B or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

ORDERING INFORMATION[†]

TA	PACKAGE	‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING§
400C to 4050C	SOT (SOT-23) – DBV	Reel of 3000	CAHCT1G32QDBVRQ1	B32_
-40°C to 125°C	SOT (SC-70) - DCK	Reel of 3000	CAHCT1G32QDCKRQ1	BG_

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

FUNCTION TABLE

INP	JTS	OUTPUT					
Α	В	Υ					
Н	Χ	Н					
Х	Н	Н					
L	L	L					

logic diagram (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡] Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

[§] The actual top-side marking has one additional character that designates the assembly/test site.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Output voltage range, VO (see Note 1)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ _{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
V _{IL}	Low-level input voltage		8.0	V
VI	Input voltage	0	5.5	V
VO	Output voltage	0	VCC	V
IOH	High-level output current		-8	mA
loL	Low-level output current		8	mA
Δt/Δν	Input transition rise or fall rate		20	ns/V
TA	Operating free-air temperature	-40	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEGT CONDITIONS		T,	Δ = 25°	С	-40°C TO 85°C		-40°C TO 125°C		LINUT	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
V	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4			
VOH	V _{OH} I _{OH} = -8 mA		3.94			3.8		3.7		V	
V	I _{OL} = 50 μA				0.1		0.1		0.1	V	
V _{OL}	I _{OL} = 8 mA	4.5 V			0.36		0.44		0.52	V	
Ц	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1		±1	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			1		10		20	μΑ	
Δl _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35		1.5		1.65	mA	
Ci	$V_I = V_{CC}$ or GND	5 V		2	10		10		10	pF	

 $[\]ddagger$ This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SN74AHCT1G32-Q1 SINGLE 2-INPUT POSITIVE-OR GATE

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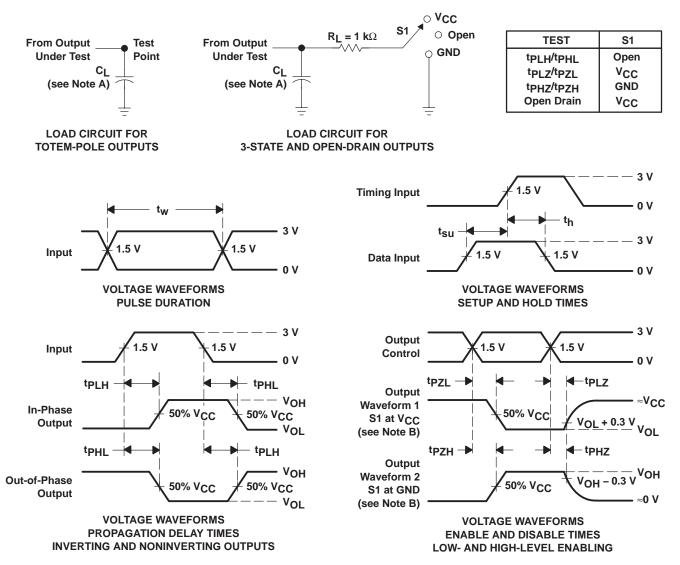
switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	T _A = 25°C			-40°C TO 85°C		-40°C TO 125°C		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
t _{PLH}	A == D	V	C _L = 15 pF		5	6.9	1	8		9.5	ns	
t _{PHL}	A or B	Y			5	6.9	1	8		9.5		
t _{PLH}	A or B	V	C 50 pF		5.5	7.9	1	9		10.5		
t _{PHL}	AOIB	'	$C_L = 50 pF$		5.5	7.9	1	9		10.5	ns	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CO	NDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	11.5	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CAHCT1G32QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	B32U	Samples
CAHCT1G32QDCKRQ1	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	BGU	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74AHCT1G32-Q1:

● Catalog: SN74AHCT1G32

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NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CAHCT1G32QDBVRQ1	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
CAHCT1G32QDCKRQ1	SC70	DCK	5	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3

www.ti.com 5-Jan-2021



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CAHCT1G32QDBVRQ1	SOT-23	DBV	5	3000	200.0	183.0	25.0
CAHCT1G32QDCKRQ1	SC70	DCK	5	3000	200.0	183.0	25.0



SMALL OUTLINE TRANSISTOR



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
 3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)



^{7.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

^{8.} Board assembly site may have different recommendations for stencil design.

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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